## PRODUCT NUMBER STRUCTURE

10164227 －AAABCDELF

## No．of Pins：

$010=10 \mathrm{Pin} ; 020=20 \mathrm{Pin} ;$
024＝24Pin；030＝30Pin；
$034=34 \mathrm{Pin} ; 040=40 \mathrm{Pin} ;$
$050=50 \mathrm{Pin} ; 060=60 \mathrm{Pin} ;$
770＝70Pin；080＝80Pin；
$090=90 \mathrm{Pin} ; 100=100 \mathrm{Pin}$ ．
$20=120 \mathrm{Pin}$
Height：
$1=1.45 \mathrm{~mm}$
Contact plating
$\mathrm{A}=$ Gold flash
$A=$ Gold flash
Hold down：
1＝Without hold down
Packing：
$R=$ Tape \＆Reel
LF：
IF＝Lead free

$12 \pm 0.02$
Pick And Place Area： $\mathrm{C} \pm 0.2$


Recommended P．C．B Layout（Top Side）


1．CURRENT RATING：0．3A ON ALL CONTACTS SIMULTANEOUSLY；
2．VOLTAGET RATING：30V AC ；
3．CONTACT RESISTANCE： $90 \mathrm{~m} \Omega$ Max；
4．WITHSTAND VOLTAGE ： 100 V AC；
5．INSULATION RESISTANCE：50M 』 Min；
6．INSULATOR MATERIAL：LCP，G．F，UL94V－0，BK；
7．CONTACT MATERIAL：Copper Alloy；
8．CONTACT PLATING：
GOLD FLASH ON CONTACT AREA（SEE ORDERING INFOMATION），
$50 \mu "$ NICKEL UNDERPLATING OVERALL；
9．CO－PLANARITY FOR CONTACT TAILS MUST BE 0.1 mm MAX
10．THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS－47－0004．
10．THE HOUSING WILL WITHSTAND EXPOSURE TO $260^{\circ} \mathrm{C}$ PEAK
TEMPERATURE FOR 1OSECONDS IN A REFLOW SOLDERING OVEN．
12．RECOMMENDED STENCIL THICKNESS IS 120um．
13．RECOMMENDED STENCIL OPENING RATIO IS $80 \%$ ．
14．PRODUCT SPEC：GS－12－1404．



## PRODUCT NUMBER STRUCTURE

10164227 －AAABCDELF

## No． 0 Pins

$\qquad$
$020=20 \mathrm{Pin} ; \quad 030=30 \mathrm{Pin} ;$
$040=40 \mathrm{Pin} ; 050=50 \mathrm{Pin}$
$060=60$ Pin； $070=70$ Pin
Height：
$2=2.4 \mathrm{~mm}$
Contact platin
$A=$ Gold flash
Hold down：
＝Without hold down
Packing：
P＝Tape \＆Reel
LF：
F＝Lead free

$\qquad$

TYP
Area： $\mathrm{C} \pm 0.2$



## Note

1．CURRENT RATING：0．3A ON ALL CONTACTS SIMULTANEOUSLY；
2．VOLTAGET RATING：30V AC
3．CONTACT RESISTANCE：90m』 Max；
4．WITHSTAND VOLTAGE ： 100 V AC；
5．INSULATION RESISTANCE：50M $\Omega$ Min；
6．INSULATOR MATERIAL：LCP，G．F，UL94V－0，BK；
7．CONTACT MATERIAL：Copper Alloy；
8．CONTACT PLATING：
GOLD FLASH ON CONTACT AREA（SEE ORDERING INFOMATION），
$50 \mu "$ NICKEL UNDERPLATING OVERALL；
9．CO－PLANARITY FOR CONTACT TAILS MUST BE 0.1 mm MAX
10．THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS－47－0004．
10．THE HOUSING WILL WITHSTAND EXPOSURE TO $260^{\circ} \mathrm{C}$ PEAK
TEMPERATURE FOR 10SECONDS IN A REFLOW SOLDERING OVEN
12．RECOMMENDED STENCIL THICKNESS IS 120 um ．
13．RECOMMENDED STENCIL OPENING RATIO IS $80 \%$ ．
14．PRODUCT SPEC：GS－12－1404．



PRODUCT NUMBER STRUCTURE
10164227 - AAABCDELF

> o.of Pins: $\quad$ _
> $30=30 \mathrm{Pin} ; 040=40 \mathrm{Pin} ;$
> $44=44 \mathrm{Pin} ; 050=50 \mathrm{Pin} ;$
> $0=60 \mathrm{Pin} ; 070=70 \mathrm{Pin} ;$
> 80=80Pin; 090=90Pin
eight:
$3=2.9 \mathrm{~mm}$
Contact plating: $\quad$ _
$A=$ Gold flash
Hold down:
=Without hold down
Pocking:
$R=$ Tape \& Re
$\stackrel{L F}{\text { LF: }}=$


Note
1.CURRENT RATING:0.3A ON ALL CONTACTS SIMULTANEOUSLY;
2.VOLTAGET RATING: 3OV AC
3.CONTACT RESISTANCE: $90 \mathrm{~m} \Omega$ Max;
4.WITHSTAND VOLTAGE : 100 V AC;
5.INSULATION RESISTANCE: $50 \mathrm{M} \Omega$ Min;
6.INSULATOR MATERIAL: LCP,G.F,UL94V-0,BK;
7.CONTACT MATERIAL: Copper Alloy;

GOLD FLASH ON CONTACT AREA(SEE ORDERING INFOMATION),
$50 \mu "$ NICKEL UNDERPLATING OVERALL;
9.CO-PLANARITY FOR CONTACT TAILS MUST BE 0.1 mm MAX.
10. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND

OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004
10. THE HOUSING WILL WITHSTAND EXPOSURE TO $260^{\circ} \mathrm{C}$ PEAK

TEMPERATURE FOR 1OSECONDS IN A REFLOW SOLDERING OVEN.
12.RECOMMENDED STENCIL THICKNESS IS 120 um .
13.RECOMMENDED STENCIL OPENING RATIO IS $80 \%$.
14.PRODUCT SPEC : GS-12-1404.
form: A3-2016-02-24
1



## PRODUCT NUMBER STRUCTURE

10164227 - AAABCDELF


LF=Lead free

## Note



1. CURRENT RATING:0.3A ON ALL CONTACTS SIMULTANEOUSLY.
2. VOLTAGET RATING: 3OV AC;
3.CONTACT RESISTANCE: $90 \mathrm{~m} \Omega$ Max;
4.WITHSTAND VOLTAGE : 100 V AC;
5.INSULATION RESISTANCE: 50M $\Omega$ Min;
6.INSULATOR MATERIAL: LCP,G.F,UL94V-0,BK;
7.CONTACT MATERIAL: Copper Alloy;
8.CONTACT PLATING:

GOLD FLASH ON CONTACT AREA(SEE ORDERING INFOMATION),
$50 \mu "$ NICKEL UNDERPLATING OVERALL;
9.CO-PLANARITY FOR CONTACT TAILS MUST BE 0.1 mm MAX.
10. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND

OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-47-0004.
10. THE HOUSING WILL WITHSTAND EXPOSURE TO $260^{\circ} \mathrm{C}$ PEAK

TEMPERATURE FOR 10 SECONDS IN A REFLOW SOLDERING OVEN.
12. RECOMMENDED STENCIL THICKNESS IS 120 um .
13.RECOMMENDED STENCIL OPENING RATIO IS 80\%.
14.PRODUCT SPEC: GS-12-1404.
form: A3-2016-02-24
1


## PRODUCT NUMBER STRUCTURE

10164227 －AAABCDELF
No．of Pins：
$020=20 \mathrm{Pin} ; 024=24 \mathrm{Pin} ;$
$030=30 \mathrm{Pin} ; 040=40 \mathrm{Pin}$,
$050=50 \mathrm{Pin} ; 060=60 \mathrm{Pin} ;$
Height：
$6=1.95 \mathrm{~mm}$
Contact plating：
A＝Gold flash
$\mathrm{B}=8 u^{\prime \prime}$ Min．Au
$\mathrm{C}=15 \mathrm{u}^{\prime \prime}$ Min．Au
Hold down：
1＝Without hold down
Packing：
$R=T$ ope \＆Red
LF：
$=$ Lead free


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－ $0.12 \pm 0.02$ ． Pick And Place Area： $\mathrm{C} \pm 0.2$


Recommended P．C．B Layout（Top Side）


## Note

1．CURRENT RATING：0．3A ON ALL CONTACTS SIMULTANEOUSLY；
2．VOLTAGET RATING：30V AC
3．CONTACT RESISTANCE： $90 \mathrm{~m} \_$Max；
4．WTHSTAND VOLTAGE： 100 V AC；
5．INSULATION RESISTANCE：50M \＆Min；
6．INSULATOR MATERIAL：LCP，G．F，UL94V－0，BK
7．CONTACT MATERIAL：Copper Alloy；
8．CONTACT PLATING：
SEE CONTACT PLATING OPTION AND ORDERING INFOMATION
$50 \mu^{\prime \prime}$ NICKEL UNDERPLATING OVERALL；
9．CO－PLANARITY FOR CONTACT TAILS MUST BE 0.1 mm MAX．
10．THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS－47－0004．
10．THE HOUSING WIL WITHSTAND EXPOSURE TO $260^{\circ} \mathrm{C}$ PEAK
TEMPERATURE FOR 1OSECONDS IN A REFLOW SOLDERING OVEN
12．RECOMMENDED STENCIL THICKNESS IS 120um．
13．RECOMMENDED STENCIL OPENING RATIO IS $80 \%$ ．
14．PRODUCT SPEC ：GS－12－1404．



